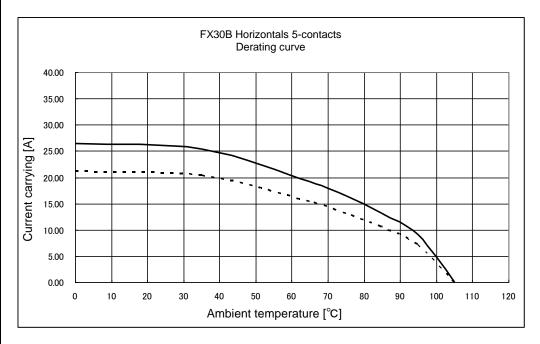
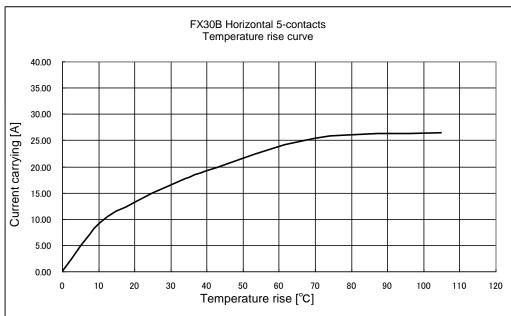
CONSTRUCTION Visually and by measuring instrument. According to drawing. X X X X X X X X X	Applic	able stand	dard 🛕	UL: UL1977, C-UL: CSA2	22.2 No.1	182.3-M1	987,	TÜV : EI	V61984	1:2009 ⁽³⁾			
RATING Current 20 A (AMBIENT TEPM 25°C) 13 A (LUC-UL) 15 A (TUV) Storage Storage Humidity Range Storage Storage Humidity Range A0 % to 70 % © STORAGE STORAGE Storage Humidity Range A0 % to 70 % © STORAGE STORAG		Volta	age 3	250 V AC/DC(UL/C-U		T	empera	ture Ra	nge				
Temperature Range	DATING	voltage /3\		150V AC/DC(TÜV)		Humidity Range					max		
SPECIFICATIONS TEST METHOD REQUIREMENTS QT A	KATING	Current $\frac{\sqrt{3}}{\sqrt{3}}$		13 A (UL/C-UL)		Tempera				-10 °C to 6		60 °C ⁽²⁾	
TEM			<u>/2\</u>	, ,		Storage Hui		Humidity	/ Rang	ange 40 % to 70			
CONSTRUCTION Seneral Examination Visually and by measuring instrument. According to drawing. x x x x x x x x x			T		IFICA	TION	S						
Semeral Examination Visually and by measuring instrument. According to drawing. X X X X X X X X X				TEST METHOD				RI	EQUII	REMENTS	QT	AT	
Marking			N/invaller									1	
LECTRIC CHARACTERISTICS 2 m Q MaX x x - model resistance 10 m A(DC or 1000Hz) 2 m Q MaX x x - model resistance 10 m A(DC or 1000Hz) x x - model resistance 10 m A(DC or 1000Hz) x x - model resistance 10 m A(DC or 1000Hz) x x - model resistance 10 m A(DC or 1000Hz) x x - model resistance 10 m A(DC or 1000Hz) x x - model resistance 10 m A(DC or 1000Hz) x x - model resistance 10 m A(DC or 1000Hz) x x - model resistance 10 m A(DC or 1000Hz) x x - model resistance 10 m A(DC or 1000Hz) x x - model resistance 10 m A(DC or 1000Hz) x x - model resistance 10 m A(DC or 1000Hz) x x - model resistance 10 m A(DC or 1000Hz) x x - model resistance 10 m A(DC or 1000Hz) x x x - model resistance 10 m A(DC or 1000Hz) x x x x x x x x x		nination					According to drawing.					×	
2 m g MAX x -		CHABAC		•							^	^	
Selection Resistance 250 V DC. 1000 M Q MIN. No flashover or breakdown. X -0							2 m () N	10 Y			T v	Ι_	
Totage Proof Tot				•								 	
MECHANICAL CHARACTERISTICS Insertion and Measured by applicable connector. Insertion Force: 25 N MAX. Withdrawal Forces: 1.0 N MIN. X - Withdrawal Forces: 1.0 N MIN. X Withdrawal Forces: 1.0 N MIN. X	Voltage Proo	f $\frac{77}{4}$							break	down.	×	 _	
Measured by applicable connector. Insertion Force: 25 N MAX X Archanical Operation 100 times insertions and extractions. ① Contact Resistance: 5 m Ω MAX. X Archanical Operation 100 times insertions and extractions. ① Contact Resistance: 5 m Ω MAX. X Archanical Operation 100 times insertions and extractions. ② No damage, crack and looseness of parts. X Archanical Operation 100 times insertions and extractions. ② No damage, crack and looseness of parts. X Archanical Operations 3 axial directions. 3 times to both directions in 3 axial directions. X Archanical Operation 100 times insertions 100 times 100 ti						I				· ·	1	1	
Production Frequency 10 to 55 to 10Hz, approx 5min Single amplitude: 0.75 mm, 10 cycles for 3 axial directions. 2 No damage, crack and looseness of parts. 3 No damage, crack and looseness of parts. 4 No damage, crack and looseness of p	Insertion and										×	-	
Trequency 10 to 55 to 10Hz, approx Smin Single amplitude : 0.75 mm, 10 cycles for 3 axial directions.	Mechanical C	peration	100 times	s insertions and extractions.							×	_	
Single amplitude : 0.75 mm, 10 cycles for 3 axial directions.								•					
for 3 axial directions. 490 m/s² , duration of pulse 11 ms, 3 times to both directions in 3 axial directions. ENVIRONMENTAL CHARACTERISTICS Bamp Heat Exposed at 40±2 °°C, 90 ~ 95 %, 96 ±4h. 20 Insulation Resistance: 5m Ω MAX. 21 Insulation Resistance: 1000 MΩ MIN. 3 No damage, crack and looseness of parts. Time 30 ~ 30 min. under 5 cycles. (Relocation time to chamber: within 2~3 MIN) Dry heat Exposed at +105±2°C for 96±4h. 25 PPM for 96h±4h. 25 PPM for 96h±4h. 25 PPM for 96h±4h. 26 No defect such as corrosion which impairs the function of connector. No deformation of case of excessive looseness of the terminal. A Soldering irons: 380°C MAX. for 10 sec. Soldering Heat COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED To immersion, duration 3 sec. COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED No. 4PPROVED HS. OKAWA 13. 03. 0 CHECKED KI. HIROKAWA 13. 03. 0 DESIGNED DK. Allw070 13. 03. 0 OESIGNED DK. Allw070 13. 03. 0 DESIGNED DK. Allw070 13. 03. 0 OESIGNED DK. Allw070 13. 03. 0 DESIGNED	Vibration									•	×	_	
Shock 490 m/s² , duration of pulse 11 ms, 3 times to both directions in 3 axial directions. X The strict of the control of the contr					S		2 No	damage	, crack	and looseness of parts.			
3 times to both directions in 3 axial directions.	Shock											 	
ENVIRONMENTAL CHARACTERISTICS Damp Heat Strady State) Exposed at 40±2 °C, 90 ~ 95 %, 96 ±4h. (2) Insulation Resistance: 5mΩ MAX. (2) Insulation Resistance: 1000 MΩ MIN. (3) No damage, crack and looseness of parts. Time 30 → 30 min. under 5 cycles. (Relocation time to chamber: within 2~3 MIN) Dry heat Exposed at +105±2°C for 96±4h. Cold Exposed at ±105±2°C for 96±4h. Cold Exposed at 25±2°C, 75±5%RH, 25 PPM for 96h±4h. Cesistance to Solder bath: Solder temperature 260±5°C for immersion, duration 10±1sec. Coldering Heat Soldering irons: 380°C MAX, for 10 sec. Colderability Soldered at solder temperature 240±3°C for immersion, duration 3 sec. COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED DATE A 2 DIS-F-00002346 To the unused product before assembly to PCB. (3) No damage, crack and looseness of parts. X - Contact Resistance: 5mΩ MAX. X - Contact Resist	Onook			•	rections								
Exposed at 40±2 °C, 90 ~ 95 %, 96 ±4h. ① Contact Resistance: 5m Ω MAX. 2 Insulation Resistance: 1000 MΩ MIN. 3 Insulation Resistance: 1000 MΩ MIN. 4 Insulation Resistance: 1000 MΩ MIN. 1 Insulation Resistance: 1000 MΩ M	FNVIRONI	MENTAL C				I						I.	
Steady State		VILITIAL C	•		96 +41	h	① Cor	ntact Res	sistanc	e:5mQ MAX	×	Ι_	
Repid Change of time 2 30 → 30 min. under 5 cycles. (Relocation time to chamber: within 2~3 MiN) Dry heat Exposed at +105±2°C for 96±4h. Cold Exposed at 25±2°C, 75±5%RH, 25 PPM for 96h±4h. Resistance to Solder bath : Solder temperature 260±5°C for immersion, duration 10±1sec. Soldering Heat Solder dat solder temperature 240±3°C for immersion, duration 3 sec. COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED DATE for the nussed product before assembly to PCB. COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED DATE for the nussed product before assembly to PCB. COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED DATE for the nussed product before assembly to PCB. COPRIGNATION OF REVISIONS DESIGNED DESIGNED RICHARD SOLD HIT. VAMAQUCHI 17. 05. 1 APPROVED HS. OKAMA 13. 03. 0 DESIGNED DK. Almotro 13.	•))	ZXPOOOG	25 70, 30 ±41.									
Time 30 → 30 min. under 5 cycles. (Relocation time to chamber: within 2~3 MIN) Exposed at +105±2°C for 96±4h. Cold Exposed at -55±2°C for 96±4h. Exposed at 25±2°C, 75±5%RH, 25 PPM for 96h±4h. Selfur Dioxide Exposed at 25±2°C, 75±5%RH, 25 PPM for 96h±4h. Resistance to Solder bath : Solder temperature 260±5°C for immersion, duration 10±1sec. Soldering Heat Soldered at solder temperature 240±3°C for immersion, duration 3 sec. Solderability Soldered at solder temperature 240±3°C for immersion, duration 3 sec. Solderability DESCRIPTION OF REVISIONS DESIGNED CHECKED DATE for immersion, duration 3 sec. Solderability DESCRIPTION OF REVISIONS DESIGNED CHECKED DATE for immersion, duration 3 sec. Solderability DESCRIPTION OF REVISIONS DESIGNED CHECKED DATE for immersion, duration 3 sec. Solderability DESCRIPTION OF REVISIONS DESIGNED CHECKED DATE for immersion, duration 3 sec. Solderability DESCRIPTION OF REVISIONS DESIGNED CHECKED DATE for the unused products before assembly to PCB. Solderability DESCRIPTION OF REVISIONS DESIGNED CHECKED HS. OKAWA 13.03.0 CHECKED KI. HIRKAWA 13.03.0 DESIGNED DK. AIMOTO 13.03.0 DESIGNED DK. DK. AIMOTO 13.03.0 DESIGNED DK. AIMOTO 13.03.0 DESIGNED DK. AIMOTO 13.03.0 DESIGNED DK. A			Temperat	ure -55 → +105 °C							×	_	
Relocation time to chamber: within 2~3 MIN) Exposed at +105±2°C for 96±4h. X - Cold Exposed at -55±2°C for 96±4h. X - Sulfur Dioxide Exposed at 25±2°C, 75±5%RH, 25 PPM for 96h±4h. 25 PPM for 96h±4h. 20 No defect such as corrosion which impairs the function of connector. No deformation of case of excessive looseness of the terminal. X - Soldering Heat Solder temperature 260±5°C for immersion, duration 10±1sec. Soldering irons: 380°C MAX. for 10 sec. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. X - Solderability Soldered at solder temperature 240±3°C for immersion, duration 3 sec. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. X - COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED DATE A 2 DIS-F-00002346 TS. 00N0 HT. YAMAGUCHI 17. 05. 1 CEMARKS (**) Include temperature rise caused by current-carrying. (**) "Storage" means a long-term storage state for the unused product before assembly to PCB. (**) Pollution degree: 2 type of terminals: dip solder contacts. DRAWN DK. AIM010 13. 03. 0 DESIGNED DK. AIM010 13. 03. 0 DESIGNED DK. AIM010 13. 03. 0 DRAWN DK. AIM010	Temperature							J	•	•			
Exposed at +105±2°C for 96±4h. Cold			under 5 c	ycles.									
Exposed at -55±2°C for 96±4h. Sulfur Dioxide Exposed at 25±2°C, 75±5%RH, 25 PPM for 96h±4h. Solder bath: Solder temperature 260±5°C for immersion, duration 10±1sec. Soldering Heat Soldering irons: 380°C MAX. for 10 sec. Solderability Soldered at solder temperature 240±3°C for immersion, duration 3 sec. COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED DATE COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED DATE COUNT COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED DATE COUNT COUNT COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED DATE COUNT COUNT COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED DATE A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. COUNT COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED CHECK			(Relocation	time to chamber: within 2~3 MII	N)								
Sulfur Dioxide Exposed at 25±2°C, 75±5%RH, 25 PPM for 96h±4h. Solder bath: Solder temperature 260±5°C for immersion, duration 10±1sec. Soldering Heat Soldered at solder temperature 240±3°C for immersion, duration 3 sec. Solderability Soldered at solder temperature 240±3°C for immersion, duration 3 sec. Solderability DESCRIPTION OF REVISIONS DESIGNED COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED DATE To immersion of case of excessive looseness of the terminal. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED DATE To immersion of case of excessive looseness of the terminal. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. CHECKED DATE APPROVED HS. OKAWA 13. 03. 0 DESIGNED CHECKED KI. HIROKAWA 13. 03. 0 DESIGNED DK. AIMOTO 13. 03. 0 DESIGNED DK. AIMOTO 13. 03. 0 DESIGNED DK. AIMOTO 13. 03. 0 DESIGNED DRAWN DK. AIMOTO 13. 03. 0 DRAWN DK. AIMOTO 14. 01/2	Dry heat		Exposed at +105±2°C for 96±4h.								×	_	
25 PPM for 96h±4h. 25 PPM for 96h±4h. 25 PPM for 96h±4h. 2 Solder bath : Solder temperature 260±5°C for immersion, duration 10±1sec. Soldering irons : 380°C MAX. for 10 sec. Solderability Soldered at solder temperature 240±3°C for immersion, duration 3 sec. Solderability Soldered at solder temperature 240±3°C for immersion, duration 3 sec. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED DATE CHECKED BRAWAS (1) Include temperature rise caused by current-carrying. (2) "Storage" means a long-term storage state for the unused product before assembly to PCB. (3) Pollution degree: 2 type of terminals : dip solder contacts. Unless otherwise specified, refer to JIS-C-5402,IEC60512. Unless otherwise specified, refer to JIS-C-5402,IEC60512. SPECIFICATION SHEET PART NO. FX30B-5P-3. 81DSA20 HIROSE ELECTRIC CO., LTD. CODE NO. CL570-3103-1-00 A 1/2	Cold		Exposed	Exposed at -55±2°C for 96±4h.							×	_	
25 PPM for 96h±4h. 2 No defect such as corrosion which impairs the function of connector. Resistance to Solder bath : Solder temperature 260±5°C for immersion, duration 10±1sec. Soldering irons : 380°C MAX. for 10 sec. Solderability Soldered at solder temperature 240±3°C for immersion, duration 3 sec. Solderability Soldered at solder temperature 240±3°C for immersion, duration 3 sec. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED DATE CHECKED DATE SEMARKS (1) Include temperature rise caused by current-carrying. (2) "Storage" means a long-term storage state for the unused product before assembly to PCB. (3) Pollution degree:2 type of terminals :dip solder contacts. Unless otherwise specified, refer to JIS-C-5402,IEC60512. Unless otherwise specified, refer to JIS-C-5402,IEC60512. SPECIFICATION SHEET PART NO. FX30B-5P-3. 81DSA20 HIROSE ELECTRIC CO., LTD. CODE NO. CL570-3103-1-00 A 1/2	Sulfur Dioxide)	Exposed	Exposed at 25±2°C. 75±5%RH.			① Contact Resistance: 5m Ω MAX.				×	_	
for immersion, duration 10±1sec. Soldering irons: 380°C MAX. for 10 sec. Solderability Soldered at solder temperature 240±3°C for immersion, duration 3 sec. COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED DATE 17.05.1 REMARKS 10 Include temperature rise caused by current-carrying. (2" Storage" means a long-term storage state for the unused product before assembly to PCB. (3) Pollution degree:2 type of terminals: dip solder contacts. Unless otherwise specified, refer to JIS-C-5402,IEC60512. Note QT:Qualification Test AT:Assurance Test X:Applicable Test SPECIFICATION SHEET PART NO. PAnew uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. A new uniform coating of solder							② No defect such as corrosion which impairs						
Soldering irons: 380°C MAX. for 10 sec. Solderability Soldered at solder temperature 240±3°C for immersion, duration 3 sec. COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED DATE 17. 05. 1 REMARKS (1) Include temperature rise caused by current-carrying. (2) "Storage" means a long-term storage state for the unused product before assembly to PCB. (3) Pollution degree:2 type of terminals:dip solder contacts. Unless otherwise specified, refer to JIS-C-5402,IEC60512. Note QT:Qualification Test AT:Assurance Test X:Applicable Test PART NO. FX30B-5P-3. 81DSA20 HIROSE ELECTRIC CO., LTD. CODE NO. CL570-3103-1-00 A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed. A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed.	Resistance to)	Solder bath : Solder temperature 260±5°C									_	
Solderability Soldered at solder temperature 240±3°C for immersion, duration 3 sec. COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED DATE TS. 00N0 HT. YAMAGUCHI 17. 05. 1 APPROVED HS. 0KAWA 13. 03. 0 CHECKED DATE APPROVED HS. 0KAWA 13. 03. 0 DESIGNED CHECKED APPROVED HIT VAMAGUCHI 17. 05. 1 APPRO	Soldering Heat		for immersion, duration 10±1sec.				of the t	erminal.					
COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED DATE 2 DIS-F-00002346 TS. 00N0 HT. YAMAGUCHI 17. 05. 1 REMARKS (1) Include temperature rise caused by current-carrying. (2) "Storage" means a long-term storage state for the unused product before assembly to PCB. (3) Pollution degree: 2 type of terminals :dip solder contacts. Unless otherwise specified, refer to JIS-C-5402,IEC60512. Note QT:Qualification Test AT:Assurance Test X:Applicable Test DRAWING NO. SPECIFICATION SHEET PART NO. FX30B-5P-3. 81DSA20 HIROSE ELECTRIC CO., LTD. CODE NO. CL570-3103-1-00		Λ	Soldering	irons: 380°C MAX. for 10 se	ec.								
COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED DATE 2 DIS-F-00002346 TS. 00N0 HT. YAMAGUCHI 17. 05. 1 REMARKS (1) Include temperature rise caused by current-carrying. (2) "Storage" means a long-term storage state for the unused product before assembly to PCB. (3) Pollution degree: 2 type of terminals :dip solder contacts. Unless otherwise specified, refer to JIS-C-5402,IEC60512. Note QT:Qualification Test AT:Assurance Test X:Applicable Test DRAWING NO. SPECIFICATION SHEET PART NO. FX30B-5P-3. 81DSA20 HIROSE ELECTRIC CO., LTD. CODE NO. CL570-3103-1-00	Caldarability		0-144	-1 l-l (0.40 l-4	000		Λ now.	ıniform o	ooting	of colder shall saver a			
2 DIS-F-00002346 TS. 00N0 HT. YAMAGUCHI 17. 05. 1 REMARKS (1) Include temperature rise caused by current-carrying. (2) "Storage" means a long-term storage state for the unused product before assembly to PCB. (3) Pollution degree:2 type of terminals :dip solder contacts. Unless otherwise specified, refer to JIS-C-5402,IEC60512. Note QT:Qualification Test AT:Assurance Test X:Applicable Test DRAWING NO. SPECIFICATION SHEET PART NO. FX30B-5P-3. 81DSA20 HIROSE ELECTRIC CO., LTD. CODE NO. CL570-3103-1-00	Solderability												
REMARKS (1) Include temperature rise caused by current-carrying. (2) "Storage" means a long-term storage state for the unused product before assembly to PCB. (3) Pollution degree:2 type of terminals :dip solder contacts. Unless otherwise specified, refer to JIS-C-5402,IEC60512. Note QT:Qualification Test AT:Assurance Test X:Applicable Test PART NO. PART NO. PART NO. PART NO. PART NO. PART NO. CL570-3103-1-00 APPROVED HS. 0KAWA 13. 03. 0 CHECKED KI. HIROKAWA 13. 03. 0 DESIGNED DK. AIMOTO DK. AIMO	COUN	T C	 ESCRIPTION	ON OF REVISIONS		DESIG	NED			CHECKED	D/	ATE	
CHECKED K1. HIROKAWA 13. 03. 0 DESIGNED DK. AIMOTO 13. 03. 0 Unless otherwise specified, refer to JIS-C-5402,IEC60512. Note QT:Qualification Test AT:Assurance Test X:Applicable Test DRAWING NO. SPECIFICATION SHEET PART NO. HIROSE ELECTRIC CO., LTD. CHECKED K1. HIROKAWA 13. 03. 0 DESIGNED DK. AIMOTO 13.						TS. 00	ONO			HT. YAMAGUCHI	17. 05. 12		
CHECKED K1. HIROKAWA 13. 03. 0 DESIGNED DK. AIMOTO DK. DK. AIMOTO DK. DK. AIMOTO DK. DK. DK. DK.	REMARKS ⁽¹⁾ Include temperature rise caused by current-carrying.						Δ		VED	HS. OKAWA	13. 03. 07		
Unless otherwise specified, refer to JIS-C-5402,IEC60512. Unless otherwise specified, refer to JIS-C-5402,IEC60512. Unless otherwise specified, refer to JIS-C-5402,IEC60512. DRAWN DK. AIMOTO 13. 03. 0 DRAWN DK. AIMOTO 13.	(•	•					CHEC	KED	KI HIROKAWA		13. 03. 07	
Unless otherwise specified, refer to JIS-C-5402,IEC60512. Note QT:Qualification Test AT:Assurance Test X:Applicable Test PART NO. PART NO. PART NO. PART NO. PART NO. CODE NO. CL570-3103-1-00 A 1/2	(•									
Acte QT:Qualification Test AT:Assurance Test X:Applicable Test DRAWING NO. ELC4-347258-00 SPECIFICATION SHEET PART NO. FX30B-5P-3. 81DSA20 HIROSE ELECTRIC CO., LTD. CODE NO. CL570-3103-1-00 1/2		, and the second	• •	·					-				
SPECIFICATION SHEET PART NO. FX30B-5P-3. 81DSA20 HIROSE ELECTRIC CO., LTD. CODE NO. CL570-3103-1-00 🛕 1/2	Unless oth	erwise spec	ified, refer	to JIS-C-5402,IEC60512	<u>.</u>	5111.111111515		DK. AIMOTO	13. 03. 07				
HIROSE ELECTRIC CO., LTD. CODE NO. CL570-3103-1-00 🛕 1/2	Note QT:Qualification Test AT:Assurance Test X:Applicable Test					DF							
								+		0	I		
			ROSE EI	OSE ELECTRIC CO., LTD.			CODE NO.		CL570-3103-1-00		4\	1/2	



[REFERENCE]





- (note 4) Derating curve takes manufacturing tolerances into consideration as well as uncertainties in temperature measurement and the measuring set up and is derived from the base curve multiplied by 0.8 calculation.
- (note 5) The value of rated current differs depending on the ambient temperature. it is recommended to use the product within the derating curve zone. if used under UL or TUV standard, please use within the standard specification.
- (note 6) Measurement method of derating curve is shown below.
 - Test Specimen: used FX30B-5P-3.81DS. used FX30B-5S-3.81DS.
 - Test condition: Turn on electricity under the static state and measure. (Test report # TR570E-20627)

Note QT:Qu	ualification Test AT:Assurance Test X:Applicable Test	DRAWIN	IG NO.	ELC4-347258-00		
HS	SPECIFICATION SHEET	PART NO. FX30B-5P-3. 81DS/			120	
	HIROSE ELECTRIC CO., LTD.	CODE NO.	CL570	0-3103-1-00	4 2	2/2